

# SEMiX453GB12Vs



SEMiX® 3s

## SEMiX453GB12Vs

### Features

- Homogeneous Si
- $V_{CE(sat)}$  with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

### Typical Applications\*

- AC inverter drives
- UPS
- Electronic Welding

### Remarks

- Case temperature limited to  $T_C=125^\circ\text{C}$  max.
- Product reliability results are valid for  $T_j=150^\circ\text{C}$
- Dynamic values apply to the following combination of resistors:  
 $R_{Gon,main} = 0,5 \Omega$   
 $R_{Goff,main} = 0,5 \Omega$   
 $R_{G,X} = 2,2 \Omega$   
 $R_{E,X} = 0,5 \Omega$



GB

### Absolute Maximum Ratings

Symbol	Conditions	Values	Unit	
<b>IGBT</b>				
$V_{CES}$	$T_j = 25^\circ\text{C}$	1200	V	
$I_C$	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	673	A
		$T_c = 80^\circ\text{C}$	513	A
$I_{Cnom}$		450	A	
$I_{CRM}$	$I_{CRM} = 3 \times I_{Cnom}$	1350	A	
$V_{GES}$		-20 ... 20	V	
$t_{psc}$	$V_{CC} = 720\text{ V}$	$T_j = 125^\circ\text{C}$	10	$\mu\text{s}$
	$V_{GE} \leq 15\text{ V}$			
	$V_{CES} \leq 1200\text{ V}$			
$T_j$		-40 ... 175	$^\circ\text{C}$	
<b>Inverse diode</b>				
$I_F$	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	516	A
		$T_c = 80^\circ\text{C}$	385	A
$I_{Fnom}$		450	A	
$I_{FRM}$	$I_{FRM} = 3 \times I_{Fnom}$	1350	A	
$I_{FSM}$	$t_p = 10\text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$	2430	A	
$T_j$		-40 ... 175	$^\circ\text{C}$	
<b>Module</b>				
$I_{t(RMS)}$	$T_{terminal} = 80^\circ\text{C}$	600	A	
$T_{stg}$		-40 ... 125	$^\circ\text{C}$	
$V_{isol}$	AC sinus 50Hz, $t = 1\text{ min}$	4000	V	

### Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
<b>IGBT</b>					
$V_{CE(sat)}$	$I_C = 450\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.75	2.2	V
		$T_j = 150^\circ\text{C}$	2.2	2.5	V
$V_{CE0}$		$T_j = 25^\circ\text{C}$	0.94	1.04	V
		$T_j = 150^\circ\text{C}$	0.88	0.98	V
$r_{CE}$	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	1.8	2.6	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$	2.9	3.4	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C = 18\text{ mA}$	5.5	6	6.5	V
$I_{CES}$	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$	$T_j = 25^\circ\text{C}$	0.1	0.3	$\text{mA}$
		$T_j = 150^\circ\text{C}$			$\text{mA}$
$C_{ies}$	$V_{CE} = 25\text{ V}$		27.0		nF
$C_{oes}$	$V_{GE} = 0\text{ V}$		2.66		nF
$C_{res}$			2.65		nF
$Q_G$	$V_{GE} = -8\text{ V} \dots +15\text{ V}$		4950		nC
$R_{Gint}$	$T_j = 25^\circ\text{C}$		1.67		$\Omega$
$t_{d(on)}$	$V_{CC} = 600\text{ V}$ $I_C = 450\text{ A}$	$T_j = 150^\circ\text{C}$	470		ns
$t_r$	$V_{GE} = \pm 15\text{ V}$	$T_j = 150^\circ\text{C}$	72		ns
$E_{on}$	$R_{Gon} = 1.4\ \Omega$	$T_j = 150^\circ\text{C}$	39.8		mJ
$t_{d(off)}$	$R_{Goff} = 1.4\ \Omega$	$T_j = 150^\circ\text{C}$	665		ns
$t_f$	$di/dt_{on} = 6400\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	109		ns
$E_{off}$	$di/dt_{off} = 4000\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	54.4		mJ
	$du/dt_{off} = 6600\text{ V}/\mu\text{s}$				
$R_{th(j-c)}$	per IGBT		0.067		K/W

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SEMiX® 3s

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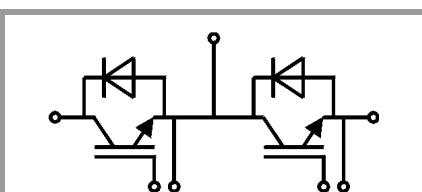
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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
<b>Inverse diode</b>						
$V_F = V_{EC}$	$I_F = 450 \text{ A}$ $V_{GE} = 0 \text{ V}$ chip	$T_j = 25^\circ\text{C}$		2.1	2.46	V
		$T_j = 150^\circ\text{C}$		2.1	2.4	V
$V_{F0}$		$T_j = 25^\circ\text{C}$	1.1	1.3	1.5	V
		$T_j = 150^\circ\text{C}$	0.7	0.9	1.1	V
$r_F$		$T_j = 25^\circ\text{C}$	1.4	1.9	2.1	m $\Omega$
		$T_j = 150^\circ\text{C}$	2.3	2.6	2.8	m $\Omega$
$I_{RRM}$	$I_F = 450 \text{ A}$	$T_j = 150^\circ\text{C}$		425		A
$Q_{rr}$	$di/dt_{off} = 6900 \text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$		78.8		$\mu\text{C}$
$E_{rr}$	$V_{GE} = -15 \text{ V}$ $V_{CC} = 600 \text{ V}$	$T_j = 150^\circ\text{C}$		32.7		mJ
$R_{th(j-c)}$	per diode				0.12	K/W
<b>Module</b>						
$L_{CE}$				20		nH
$R_{CC'+EE'}$	res., terminal-chip	$T_C = 25^\circ\text{C}$		0.7		m $\Omega$
		$T_C = 125^\circ\text{C}$		1		m $\Omega$
$R_{th(c-s)}$	per module			0.04		K/W
$M_s$	to heat sink (M5)		3		5	Nm
$M_t$		to terminals (M6)	2.5		5	Nm
						Nm
$w$					300	g
<b>Temperatur Sensor</b>						
$R_{100}$	$T_C=100^\circ\text{C}$ ( $R_{25}=5 \text{ k}\Omega$ )			$493 \pm 5\%$		$\Omega$
$B_{100/125}$	$R(T)=R_{100}\exp[B_{100/125}(1/T-1/T_{100})]$ ; $T[\text{K}]$ ;			$3550 \pm 2\%$		K



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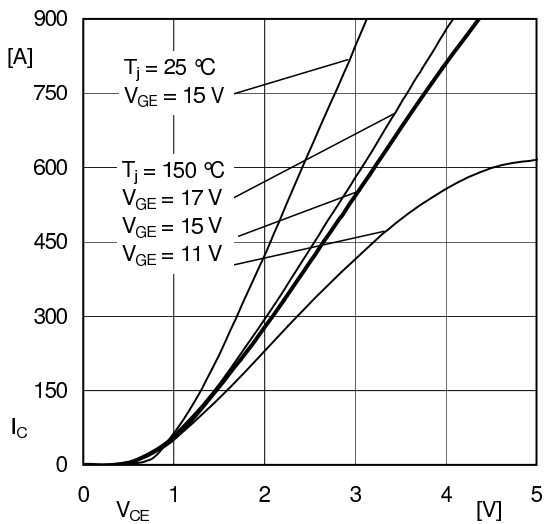


Fig. 1: Typ. output characteristic, inclusive R<sub>CC+EE</sub>

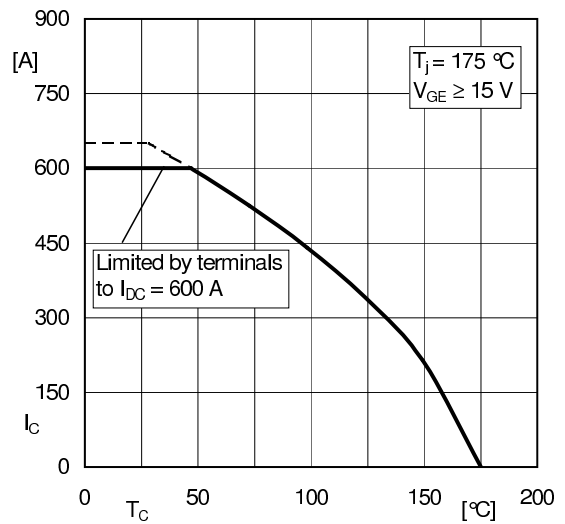


Fig. 2: Rated current vs. temperature I<sub>C</sub> = f(T<sub>C</sub>)

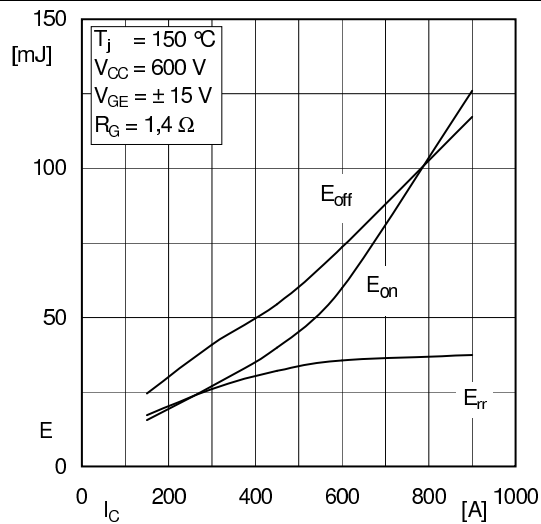


Fig. 3: Typ. turn-on /-off energy = f(I<sub>C</sub>)

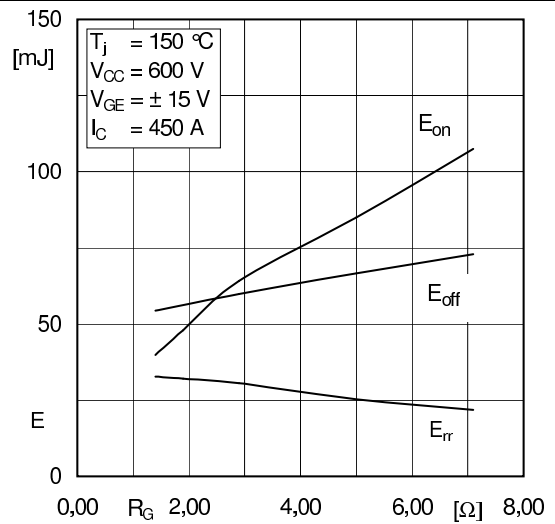


Fig. 4: Typ. turn-on /-off energy = f(R<sub>G</sub>)

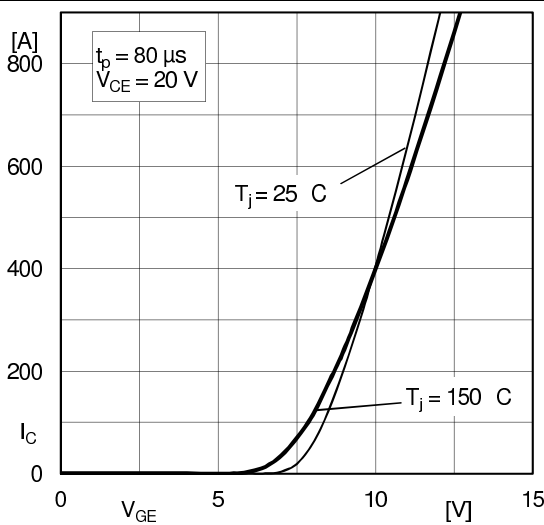


Fig. 5: Typ. transfer characteristic

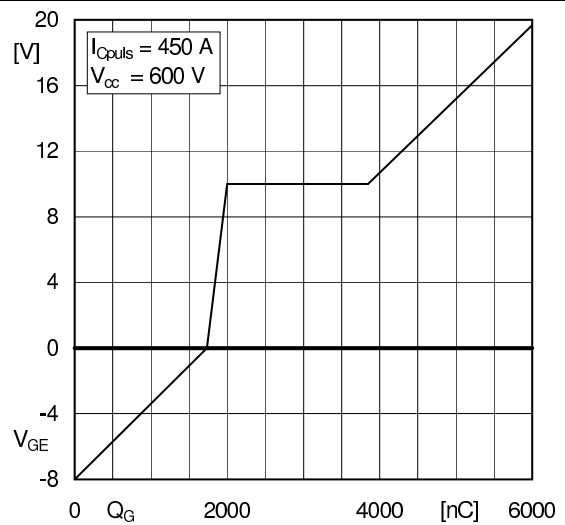


Fig. 6: Typ. gate charge characteristic

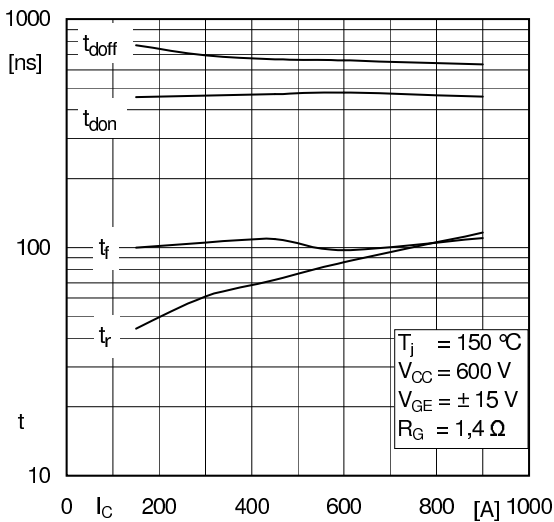


Fig. 7: Typ. switching times vs.  $I_C$

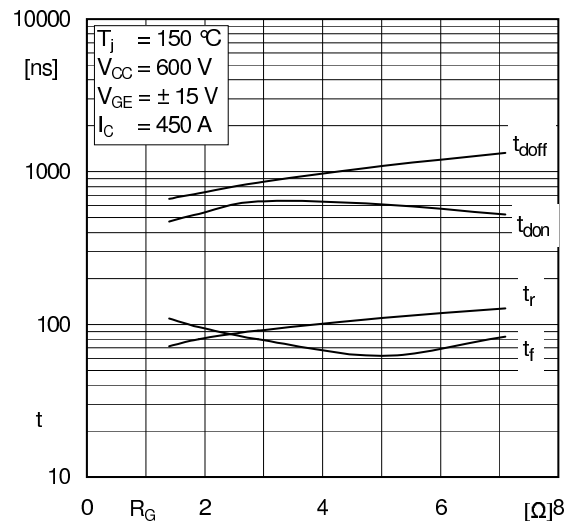


Fig. 8: Typ. switching times vs. gate resistor  $R_G$

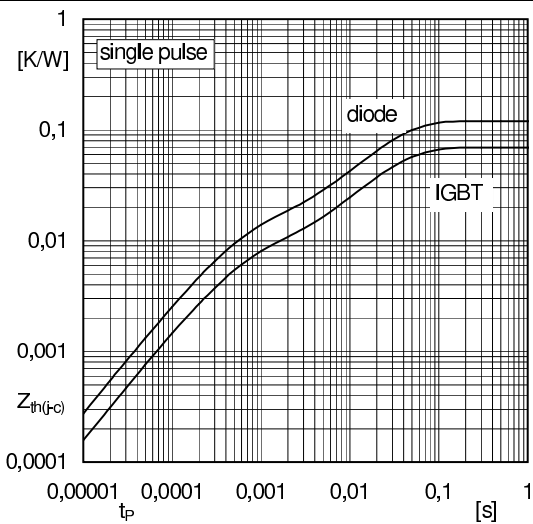


Fig. 9: Typ. transient thermal impedance

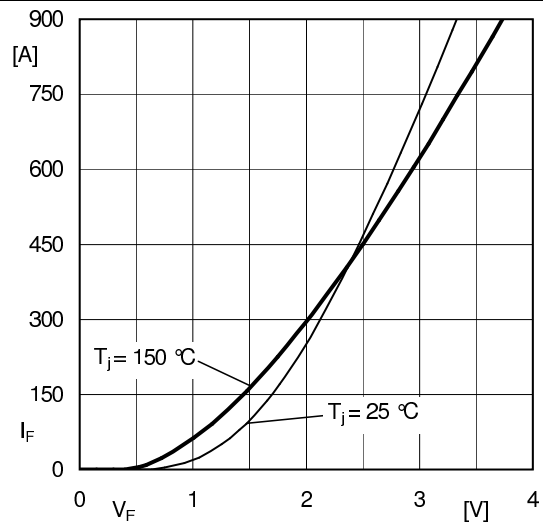


Fig. 10: Typ. CAL diode forward charact., incl.  $R_{CC+EE}$

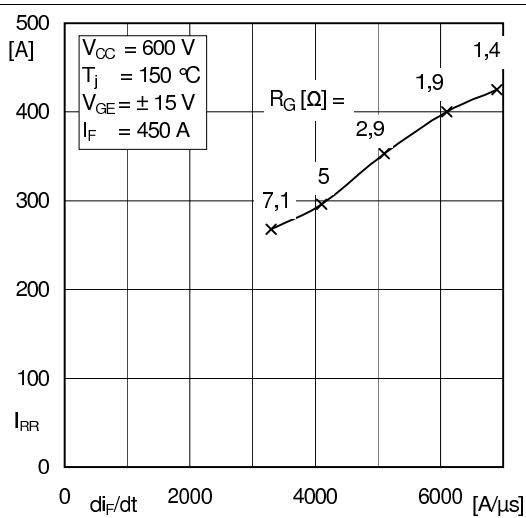


Fig. 11: Typ. CAL diode peak reverse recovery current

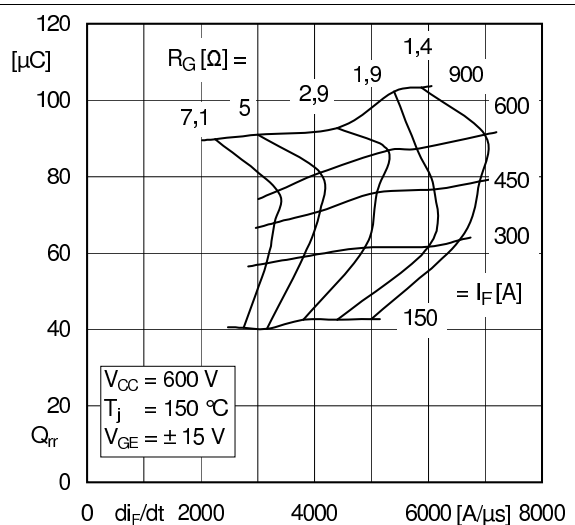


Fig. 12: Typ. CAL diode recovery charge

